

- "B" holes must remain OPEN after solder phase. - When THT components aren't mannted

		Description	u 0					Ś	Symbol STSPIN3264	3264
		¥	ASSEMBLY DRAWING	IBL Y	D	I M A	<u></u> ا	9	Group	
AMS Group AGRA	AGRATE B. ITALY								EVSPIN3264-DUAL	34 - DUAL
ALL RIGHTS STRICTLY RESERV	'ED. REPRO-	TOLER	TOLERANCE UNLESS NOTED	UNLE	SS N	OIED		150	L SCALE:	REV.
DUCTION OR ISSUE TO THIRD PARTIES IN	PARTIES IN		N O	UNIT=MM			Ψ_	† †	$- \bigoplus_{i=1}^{n} 2 : 1 \qquad 1.$	1.0
ANT FORM WHALEVER IS NOT WITHOUT WRITTEN AUTHORIZA	FERMITTED		0	0 >10 >50	>50		ANG. Materia	rial		
STMicroelectron	ics.	Inear	<10	<10 <50 <200 >200	<200		LES.			
Drawn date	د						<u> </u>			
RIGO M. 12	12-Jan-2022 midle		±0.1	±0.2	±0.3	±0.5	±¹ Treat	nen† an	± 0.1 ± 0.2 ± 0.3 ± 0.5 ± 1 Treatment and surface finishing	ing
Approved date	٥						T *			
		accurate +0.05 +0.1 +0.15 +0.25 +30	+0.05	+0.1	0.15	+0.25	+30			

⁻ When THT components aren't mounted, your holes must remains OPEN after solder phase.